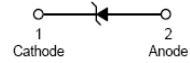


Features

- Tight voltage tolerance: $\pm 5\%$
- Ultra low-profile package well suited for automated assembly
- Moisture sensitivity level 1
- Halogen free
- Qualified to AEC-Q101 standards for high reliability

HF



SOD-323

Mechanical Data

- Case: SOD-323
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TMMSZ4697S	SOD-323	3000 pcs / Tape & Reel	DE

Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation	P_D	200	mW
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	625	$^{\circ}\text{C/W}$
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	337	$^{\circ}\text{C/W}$
Operating Junction Temperature Range	T_J	-55 ~ +150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-65 ~ +150	$^{\circ}\text{C}$

Note: These ratings are limiting values above which the serviceability of the diodes may be impaired

Electrical Characteristics (@ $T_A = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Zener Voltage	V_Z	$I_{ZT} = 50\mu\text{A}$	9.5	10	10.5	V
Maximum Reverse Current	I_R	$V_R = 7.6\text{V}$	-	-	1	μA

TYPICAL CHARACTERISTICS (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

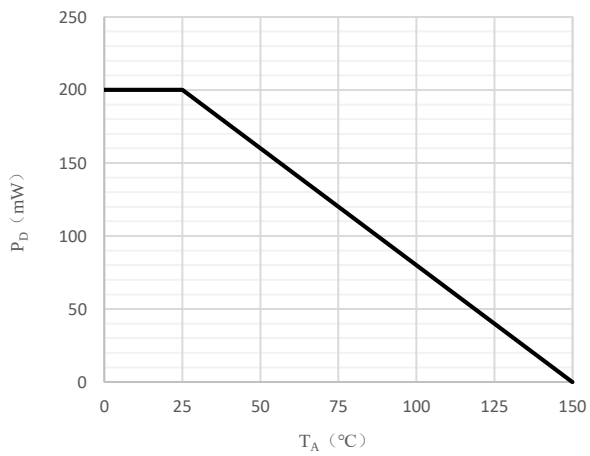


Fig 1 Steady State Power Derating

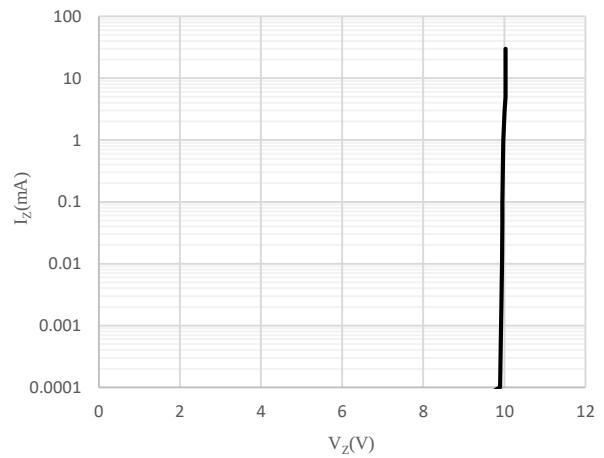
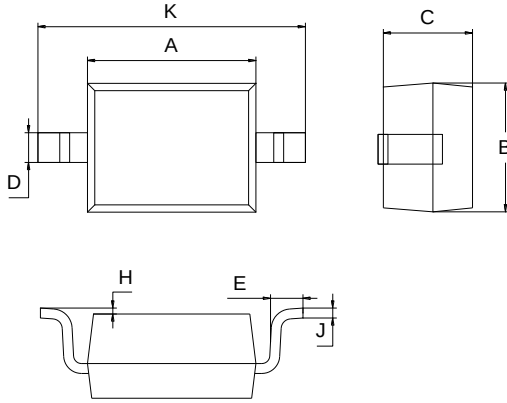


Fig 2 Typical Zener Breakdown Characteristics

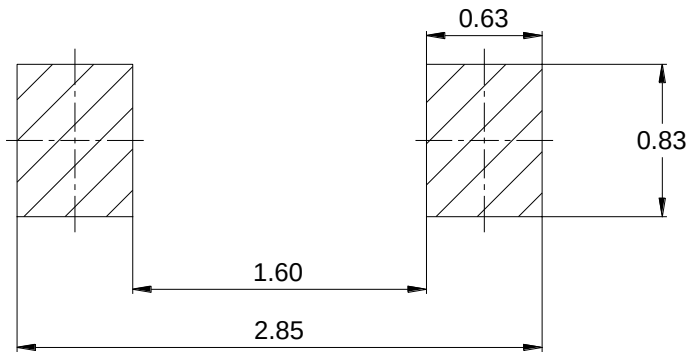
Package Outline Dimensions (Unit: mm)



SOD-323		
Dimension	Min.	Max.
A	1.60	1.80
B	1.20	1.40
C	0.80	0.90
D	0.25	0.35
E	0.22	0.42
H	0.02	0.10
J	0.05	0.15
K	2.55	2.75

Package Outline Dimensions (Unit: mm)

SOD-323



Important Notice

Changzhou Galaxy Century Microelectronics (GME) reserves the right to make changes without further notice to any product information (copyrighted) herein to make corrections, modifications, improvements, or other changes. GME does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others.